Product / Package Information	
Package	TQFP_EP
Body Size (mm)	14 X 14 X 1.0 (8.0 EP)
Lead Count	100
Terminal Finish	100 Sn

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A and B

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica fused	60676-86-0	2.63E-01	88	880000	49.70	496975
Thermosets	Epoxy & Phenol resin	Proprietary	3.44E-02	11.5	115000	6.49	64946
Other inorganic materials	Carbon black	1333-86-4	1.49E-03	0.5	5000	0.28	2824
Subtotal			2.99 E-01	100.00	1000000	56.47	564744

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.53E-01	99.25	992500	29.02	290152
Copper & its alloys	Chromium	7440-47-3	4.64E-04	0.30	3000	0.09	877
Copper & its alloys	Tin	7440-31-5	3.87E-04	0.25	2500	0.07	731
Copper & its alloys	Zinc	7440-66-6	3.09E-04	0.20	2000	0.06	585
Subtotal			1.55 E-01	100.00	1000000	29.23	292345

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	1.28 E-03	100.0	1000000	0.24	2420

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.08 E-02	100.0	1000000	2.04	20419

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	2.10 E-03	100.00	1000000	0.40	3970

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.35 E-02	100.0	1000000	10.11	101129

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	5.73E-03	72.40	724000	1.08	10841
Thermoset	Epoxy compound	Proprietary	1.43E-03	18.10	181000	0.27	2710
Other organic materials	Anhydrides	Proprietary	5.38E-04	6.79	67900	0.10	1017
Other organic materials	Polymeric material	Proprietary	2.15E-04	2.71	27100	0.04	406
Subtotal	Subtotal		7.92 E-03	100.00	1000000	1.50	14974

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.29 E-01**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	TQFP_EP
Body Size (mm)	14 X 14 X 1.0 (8.0 EP)
Lead Count	100
Terminal Finish	SnPb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
JIG Material Content Compliant	No

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica fused	60676-86-0	2.63E-01	88	880000	49.70	496975
Thermosets	Epoxy & Phenol resin	Proprietary	3.44E-02	11.5	115000	6.49	64946
Other inorganic materials	Carbon black	1333-86-4	1.49E-03	0.5	5000	0.28	2824
Subtotal			2.99 E-01	100.00	1000000	56.47	564744

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.53E-01	99.25	992500	29.02	290152
Copper & its alloys	Chromium	7440-47-3	4.64E-04	0.30	3000	0.09	877
Copper & its alloys	Tin	7440-31-5	3.87E-04	0.25	2500	0.07	731
Copper & its alloys	Zinc	7440-66-6	3.09E-04	0.20	2000	0.06	585
Subtotal			1.55 E-01	100.00	1000000	29.23	292345

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	1.28 E-03	100.0	1000000	0.24	2420

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.18 E-03	85.0	850000	1.74	17356
Tin & its alloys	Lead	7439-92-1	1.62 E-03	15.0	150000	0.31	3063
Subtotal			1.08 E-02	100.0	1000000	2.04	20419

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	2.10 E-03	100.00	1000000	0.40	3970

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.35 E-02	100.0	1000000	10.11	101129

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	5.73E-03	72.40	724000	1.08	10841
Thermoset	Epoxy compound	Proprietary	1.43E-03	18.10	181000	0.27	2710
Other organic materials	Anhydrides	Proprietary	5.38E-04	6.79	67900	0.10	1017
Other organic materials	Polymeric material	Proprietary	2.15E-04	2.71	27100	0.04	406
Subtotal	Subtotal		7.92 E-03	100.00	1000000	1.50	14974

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.29 E-01**	100.00	1000000

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